

# **CGHV27030S**

## 30 W, DC - 6.0 GHz, GaN HEMT

The CGHV27030S is an unmatched, gallium nitride (GaN) high electron mobility transistor (HEMT) which offers high efficiency, high gain and wide bandwidth capabilities. The CGHV27030S GaN HEMT devices are ideal for telecommunications applications with frequencies of 700-960 MHz, 1200-1400 MHz, 1800-2200 MHz, 2500-2700 MHz, and 3300-3700 MHz at both 50 V and 28 V operations. The CGHV27030S is also ideal for tactical communications applications operating from 20-2500 MHz, including land mobile radios. Additional applications include L-Band

VEREE S

Package Type: 3x4 DFN PN: CGHV27030S

RADAR and S-Band RADAR. The CGHV27030S can operate with either a 50 V or 28 V rail. The transistor is available in a 3mm x 4mm, surface mount, dual-flat-no-lead (DFN) package.

## Typical Performance 2.5-2.7 GHz ( $T_c = 25^{\circ}C$ ), 50 V

Parameter	2.5 GHz	2.6 GHz	2.7 GHz	Units
Small Signal Gain	22.5	22.0	21.4	dB
Adjacent Channel Power @ P <sub>OUT</sub> =5 W	-34.5	-35.0	-34.0	dBc
Drain Efficiency @ P <sub>OUT</sub> = 5 W	28.5	29.5	30.0	%
Input Return Loss	8.5	14	14	dB

#### Note:

Measured in the CGHV27030S-AMP1 application circuit, under 7.5 dB PAR single carrier WCDMA signal test model 1 with 64 DPCH.

### Features for 50 V in CGHV27030S-AMP1

- 2.5 2.7 GHz Operation
- 30 W Typical Output Power
- 20 dB Gain at 5 W P<sub>AVE</sub>
- -34 dBc ACLR at 5 W P<sub>AVE</sub>
- 30% efficiency at 5 W P<sub>AVE</sub>
- High degree of APD and DPD correction can be applied

Large Signal Models Available for ADS and MWO

### Listing of Available Hardware Application Circuits / Demonstration Circuits

Application Circuit	Operating Frequency	Amplifier Class	Operating Voltage
CGHV27030S-AMP1	2.5 - 2.7 GHz	Class A/B	50 V
CGHV27030S-AMP2	2.5 - 2.7 GHz	Class A/B	28 V
CGHV27030S-AMP3	1.8 - 2.2 GHz	Class A/B	28 V
CGHV27030S-AMP4	1.8 - 2.2 GHz	Class A/B	50 V
CGHV27030S-AMP5	1.2 - 1.4 GHz	Class A/B	50 V



#### Absolute Maximum Ratings (not simultaneous) at 25°C Case Temperature

Parameter	Symbol	Rating	Units	Notes
Drain-Source Voltage	$V_{\scriptscriptstyle DSS}$	125	Volts	25°C
Gate-to-Source Voltage	$V_{\sf GS}$	-10, +2	Volts	25°C
Storage Temperature	$T_{\mathtt{STG}}$	-65, +150	°C	
Operating Junction Temperature	$T_{_{J}}$	225	°C	
Maximum Forward Gate Current	I <sub>GMAX</sub>	4	mA	25°C
Maximum Drain Current <sup>1</sup>	I <sub>DMAX</sub>	1.5	Α	25°C
Soldering Temperature <sup>2</sup>	$T_s$	245	°C	
Case Operating Temperature <sup>3</sup>	T <sub>c</sub>	-40, +150	°C	
Thermal Resistance, Junction to Case <sup>4</sup>	$R_{\theta JC}$	6.18	°C/W	85°C

#### Note:

# Electrical Characteristics (T<sub>c</sub> = 25°C)

Characteristics	Symbol	Min.	Тур.	Max.	Units	Conditions
DC Characteristics <sup>1</sup>						
Gate Threshold Voltage	$V_{\rm GS(th)}$	-3.8	-3.0	-2.3	V <sub>DC</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 4 mA
Gate Quiescent Voltage	$V_{\rm GS(Q)}$	-	-2.7	-	V <sub>DC</sub>	$V_{DS} = 50 \text{ V, } I_{D} = 0.13 \text{ mA}$
Saturated Drain Current	I <sub>DS</sub>	3.0	3.6	-	А	$V_{DS} = 6.0 \text{ V}, V_{GS} = 2.0 \text{ V}$
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	150	-	-	V <sub>DC</sub>	$V_{GS} = -8 \text{ V, } I_D = 4 \text{ mA}$
RF Characteristics <sup>2,3</sup> (T <sub>c</sub> = 25°C, F <sub>0</sub> = 2.65 GHz	unless otherv	vise noted)				
Gain	G	20	23	-	dB	$V_{DD} = 50 \text{ V, } I_{DQ} = 0.13 \text{ A, } P_{IN} = 10 \text{ dBm}$
Output Power <sup>4</sup>	P <sub>out</sub>	44.5	45	-	dBm	$V_{DD} = 50 \text{ V, } I_{DQ} = 0.13 \text{ A, } P_{IN} = 28 \text{ dBm}$
Drain Efficiency <sup>4</sup>	η	64	73	-	%	$V_{DD} = 50 \text{ V, } I_{DQ} = 0.13 \text{ A, } P_{IN} = 28 \text{ dBm}$
Output Mismatch Stress <sup>4</sup>	VSWR	-	10:1	-	Ψ	No damage at all phase angles, $V_{DD} = 50 \text{ V, } I_{DQ} = 0.13 \text{ A, } P_{IN} = 28 \text{ dBm}$
Dynamic Characteristics						
Input Capacitance <sup>5</sup>	C <sub>gs</sub>	-	5.38	-	pF	$V_{DS} = 50 \text{ V, } V_{gs} = -8 \text{ V, f} = 1 \text{ MHz}$
Output Capacitance <sup>5</sup>	C <sub>DS</sub>	-	1.18	-	pF	$V_{DS} = 50 \text{ V, } V_{gs} = -8 \text{ V, f} = 1 \text{ MHz}$
Feedback Capacitance	$C_{GD}$	-	0.12	-	pF	$V_{DS} = 50 \text{ V, } V_{gs} = -8 \text{ V, } f = 1 \text{ MHz}$

#### Notes:

<sup>&</sup>lt;sup>1</sup> Current limit for long term, reliable operation

<sup>&</sup>lt;sup>2</sup> Refer to the Application Note on soldering at <a href="https://www.cree.com/rf/document-library">www.cree.com/rf/document-library</a>

 $<sup>^{3}</sup>$  T<sub>c</sub> = Case temperature for the device. It refers to the temperature at the ground tab underneath the package. The PCB will add additional thermal resistance. See also, the Power Dissipation De-rating Curve on page 23.

 $<sup>^{\</sup>rm 4}$  Measured for the CGHV27030S at P  $_{\rm DISS}$  = 12 W

 $<sup>^{5}</sup>$  The R $_{TH}$  for Cree's demonstration amplifier, CGHV27030S-AMP1, with 33 x 0.011 via holes designed on a 20 mil thick Rogers 4350 PCB, is 3.9°C. The total R $_{TH}$  from the heat sink to the junction is 6.18°C + 3.9°C = 10.08°C/W.

<sup>&</sup>lt;sup>1</sup> Measured on wafer prior to packaging

<sup>&</sup>lt;sup>2</sup> Scaled from PCM data

 $<sup>^{\</sup>rm 3}$  Measured in Cree's production test fixture. This fixture is designed for high volume test at 2.65 GHz

 $<sup>^4</sup>$  Un-modulated  $\,$  Pulsed Signal 100  $\mu s,\,10\%$  duty cycle

<sup>&</sup>lt;sup>5</sup> Includes package parasitics.

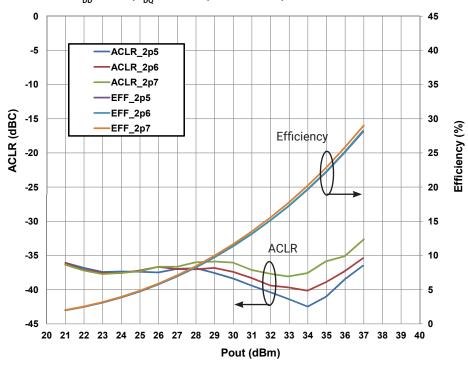




 $V_{DD} = 50 \text{ V, } I_{DO} = 0.13 \text{ A}$ 30 25 20 Gain (dB) Input and Output Return Loss 15 10 0 -5 S11 -15 S21 -20 S22 -25 2200 2300 2400 2500 2700 2800 3000 3100 3200 Frequency (MHz)

Figure 1. - Small Signal Gain and Return Losses vs Frequency

Figure 2. - Typical Drain Efficiency and ACLR vs. Output Power  $V_{DD} = 50 \text{ V, } I_{DQ} = 0.13 \text{ A, } 1c \text{ WCDMA, } PAR = 7.5 \text{ dB}$ 





# Typical Performance in Application Circuit CGHV27030S-AMP1

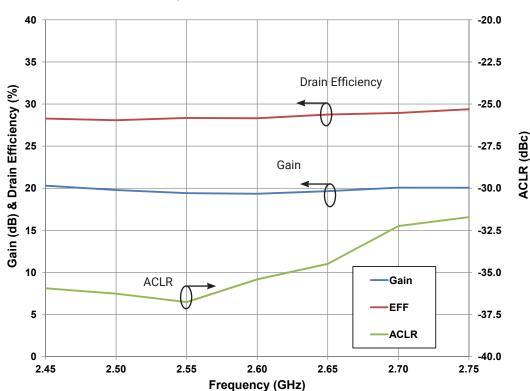
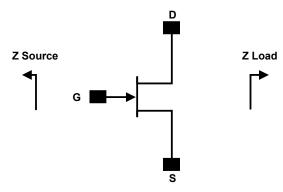


Figure 3. - Typical Gain, Drain Efficiency and ACLR vs Frequency  $V_{DD}$  = 50 V ,  $I_{DQ}$  = 0.13 A,  $P_{AVE}$  = 5 W, 1c WCDMA, PAR = 7.5 dB





Frequency (MHz)	Z Source	Z Load
2500	2.2 - j0.7	10.9 + j15.7
2600	2.8 - j1.1	11.5 + j16.7
2700	2.5 - j1.7	12.1+j17.7

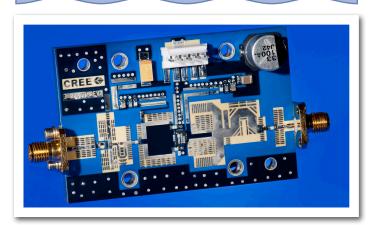
Note<sup>1</sup>:  $V_{DD}$  = 50 V,  $I_{DQ}$  = 0.13 A in the DFN package.

Note<sup>2</sup>: Impedances are extracted from the CGHV27030S-AMP1 application circuit and are not source and load pull data derived from the transistor.

### CGHV27030S-AMP1 Bill of Materials

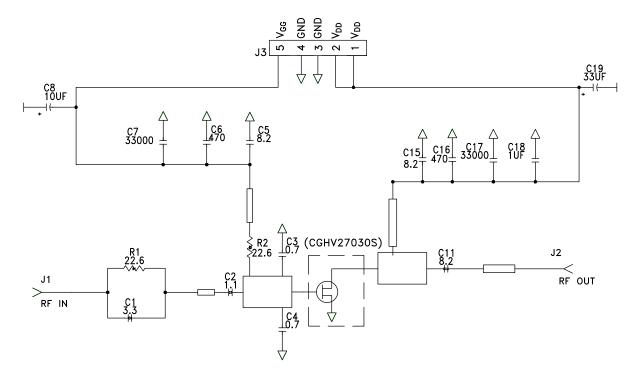
Designator	Description	Qty
R1, R2	RES, 22.6, OHM, +/-1%, 1/16W, 0603	2
C1	CAP, 3.3 pF, ±0.1 pF, 0603, ATC	1
C2	CAP, 1.1 pF, ±0.05 pF, 0603, ATC	1
C3, C4	CAP, 0.7 pF, ±0.05 pF, 0603, ATC	3
C5, C11, C15	CAP, 8.2 pF, ±0.25 pF, 0603, ATC	3
C6, C16	CAP, 470 pF, 5%, 100 V, 0603	2
C7, C17	CAP, 33000 pF, 0805, 100 V, 0603, X7R	2
C18	CAP, 1.0 UF, 100 V, 10%, X7R, 1210	1
C8	CAP, 10 UF 16 V TANTALUM	1
C19	CAP, 33 UF, 20%, G CASE	1
J1, J2	CONN, SMA, PANEL MOUNT JACK, FLANGE, 4-HOLE, BLUNT POST	2
J3	HEADER RT>PLZ .1CEN LK 5 POS	1
РСВ	PCB, ROGERS 4350, ER 3.66	1
Q1	CGHV27030S, QFN	1

## **CGHV27030S - AMP1 Application Circuit**

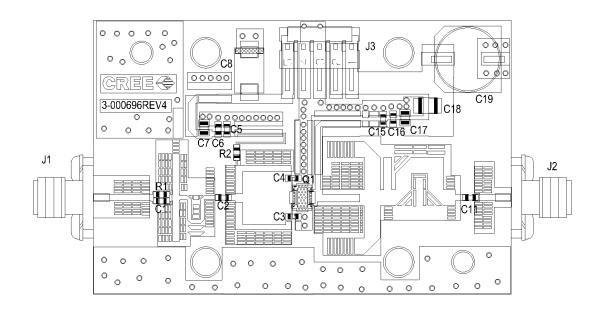




## CGHV27030S-AMP1 Application Circuit Schematic, 50 V



## CGHV27030S-AMP1 Application Circuit Outline, 50 V

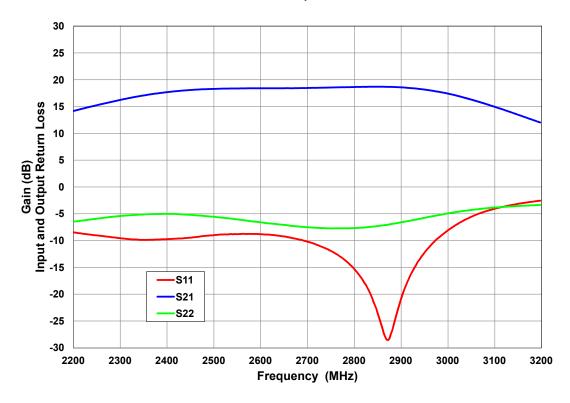




# Electrical Characteristics When Tested in CGHV27030S-AMP2, 28 V, 2.5 - 2.7 GHz

Parameter	2.5 GHz	2.6 GHz	2.7 GHz	Units
Small Signal Gain	15.5	15.7	16.0	dB
Adjacent Channel Power @ P <sub>OUT</sub> =3.2 W	-42.0	-41.7	-41.2	dBc
Drain Efficiency @ P <sub>OUT</sub> = 3.2 W	33.5	34.2	34.1	%
Input Return Loss	-9.0	-8.8	-10.2	dB

Figure 4. - Small Signal Gain and Return Losses vs Frequency  $V_{\mbox{\tiny DD}}$  = 28 V,  $I_{\mbox{\tiny DQ}}$  = 0.13 A







0 45 ACLR\_2p5 -5 40 ACLR\_2p6 35 -10 ACLR\_2p7 EFF2P5 -15 30 EFF2P6 EFF2P7 25 (%) 20 Efficiency (%) -20 -25 15 -30 10 -35 -40 5 -45 18 19 20 21 22 23 24 25 26 27 28 29 30 31 32 33 34 35 36 37 38 Pout (dBm)

Figure 5. - Typical Drain Efficiency and ACLR vs. Output Power  $V_{DD}$  = 28 V,  $I_{DQ}$  = 0.13 A, 1c WCDMA, PAR = 7.5 dB ACLR(dBc)

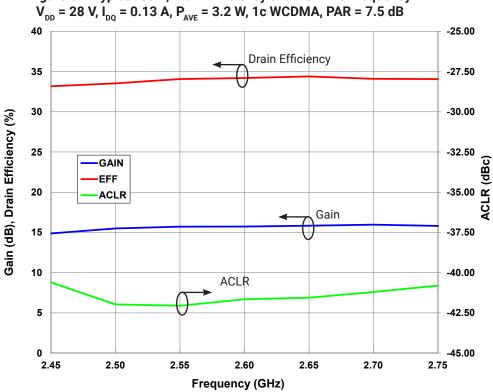
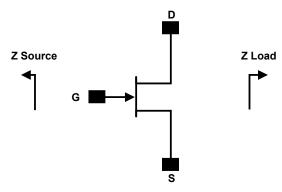


Figure 6. - Typical Gain, Drain Efficiency and ACLR vs Frequency





Frequency (MHz)	Z Source	Z Load
2500	2.9 - j2.7	14.5 + j7.4
2600	3.1 - j2.9	13.8 + j7.3
2700	2.7 - j3.1	12.9+j7.6

Note<sup>1</sup>:  $V_{DD}$  = 28 V,  $I_{DQ}$  = 0.13 A in the DFN package. Note<sup>2</sup>: Impedances are extracted from the CGHV27030S-AMP2 application circuit and are not source and load pull data derived from the transistor

### CGHV27030S-AMP2 Bill of Materials

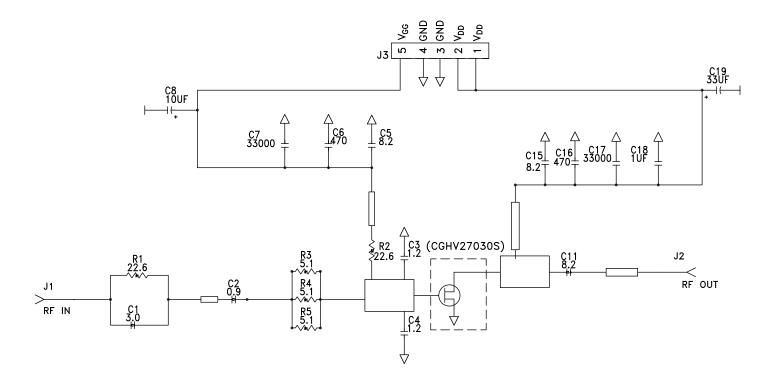
#### Description Designator Qty RES, 22.6, OHM, +/-1%, 1/16W, 0603 R1, R2 2 C1 CAP, 3.0 pF, ±0.1 pF, 0603, ATC C2 CAP, 0.9 pF, ±0.05 pF, 0603, ATC 3 R3,R4,R5 RES, 1/16W, 0603, 1%, 5.1% OHMS C3,C4 CAP, 1.2 pF, +/-0.1 pF, 0603, ATC C5, C11, C15 CAP, 8.2 pF, ±0.25 pF, 0603, ATC C6, C16 CAP, 470 pF, 5%, 100 V, 0603 C7, C17 CAP, 33000 pF, 0805, 100 V, 0603, X7R C18 CAP, 1.0 UF, 100 V, 10%, X7R, 1210 C8 CAP, 10 UF 16 V TANTALUM C19 CAP, 33 UF, 20%, G CASE J1, J2 CONN, SMA, PANEL MOUNT JACK HEADER RT>PLZ .1CEN LK 5 POS J3 PCB PCB, ROGERS 4350, ER 3.66 CGHV27030S, QFN Q1

### **CGHV27030S-AMP2 Application Circuit**

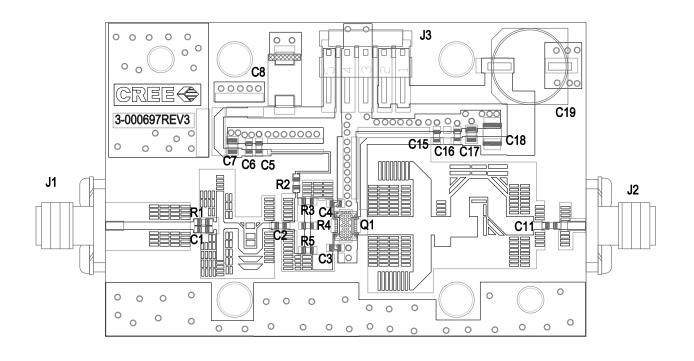




### CGHV27030S-AMP2 Application Circuit Schematic, 28 V



### CGHV27030S-AMP2 Application Circuit Outline, 28 V

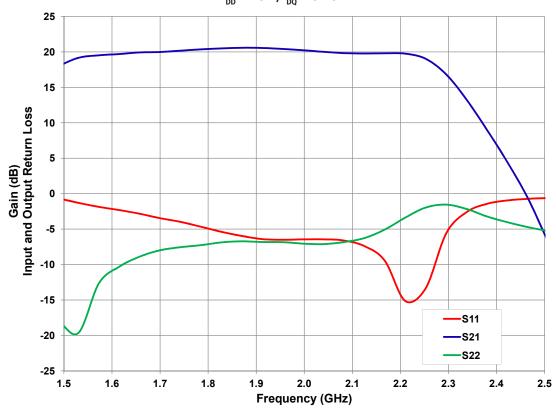




# Electrical Characteristics When Tested in CGHV27030S-AMP3, 28 V, 1.8 - 2.2 GHz

Parameter	1.8 GHz	2.0 GHz	2.2 GHz	Units
Small Signal Gain	19	19	18	dB
Adjacent Channel Power @ P <sub>OUT</sub> =3.2 W	-37	-38	-39	dBc
Drain Efficiency @ P <sub>out</sub> = 3.2 W	35	35	33	%
Input Return Loss	5	6	7	dB

Figure 7. - Small Signal Gain and Return Losses vs Frequency  $V_{DD}$  = 28 V,  $I_{DO}$  = 0.13 A





-40

-45

-50 <del>|</del> 20

22

24

26



60 -5 ACLR\_1p8 -ACLR\_2p0 -10 -ACLR\_2p2 -15 DE\_1p8 Drain Efficiency ( %) DE\_2p0 -20 ACLR (dBc) -DE\_2p2 -25 -30 -35

Figure 8. - Typical Drain Efficiency and ACLR vs. Output Power  $V_{_{\rm DD}}$  = 28 V,  $I_{_{\rm DQ}}$  = 0.13 A, 1c WCDMA, PAR = 7.5 dB

Figure 9. - Typical Gain, Drain Efficiency and ACLR vs Frequency  $V_{DD}$  = 28 V,  $I_{DQ}$  = 0.13 A,  $P_{AVE}$  = 3.2 W, 1c WCDMA, PAR = 7.5 dB

Output Power (dBm)

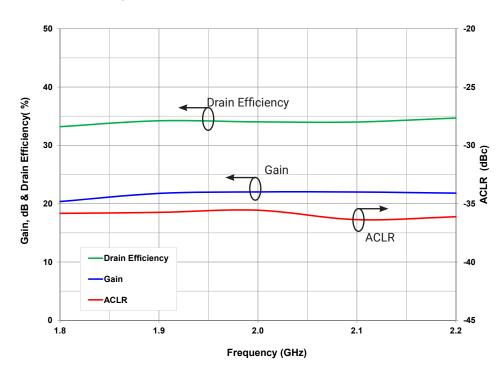
28

30

32

34

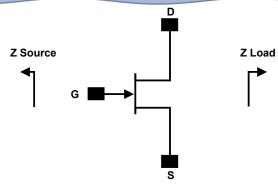
36



10

38





Frequency (MHz)	Z Source	Z Load
1800	6.16 - j3.5	21.9 + j6.5
2000	6.8 - j1.7	21 + j8.4
2200	5.5 - j2.0	20.8 + j11

Note<sup>1</sup>:  $V_{DD}$  = 28 V,  $I_{DQ}$  = 0.13 A in the DFN package. Note<sup>2</sup>: Impedances are extracted from the CGHV27030S-AMP3 application circuit and are not source and load pull data derived from the transistor

### **CGHV27030S-AMP3 Bill of Materials**

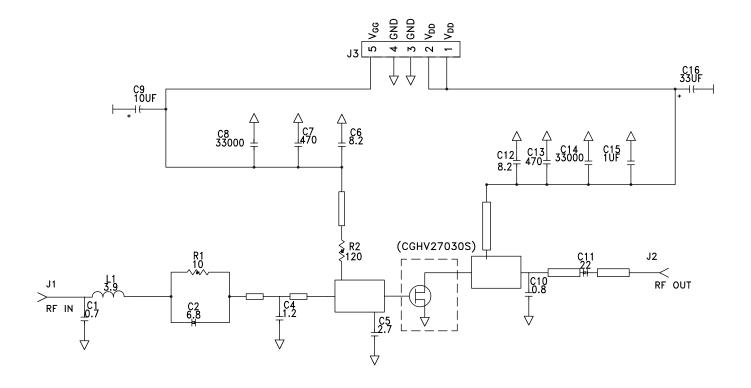
Designator	Description	Qty
R1	RES, 10, OHM, +/-1%, 1/16W, 0603	1
R2	RES, 120, OHM, +/-1%, 1/16W, 0603	1
L1	IND, 3.9 nH, +/-5%, 0603, JOHANSON	1
C1	CAP, 0.7 pF, +/-0.1 pF, 0603, ATC	1
C2	CAP, 6.8 pF, +/-5%, 0603, ATC	1
C3	CAP, 47pF, +/-0.1 pF, 0603, ATC	1
C4	CAP, 1.5 pF, +/-0.1 pF, 0603, ATC	1
C5	CAP, 2.7 pF, +/-0.1 pF, 0603, ATC	1
C6, C12	CAP, 8.2 pF, +/-0.25 pF, 0603, ATC	2
C7, C13	CAP, 470 pF, 5%, 100 V, 0603	2
C8, C14	CAP, 33000 pF, 0805, X7R	2
C9	CAP 10 UF 16 V TANTALUM	1
C10	CAP, 0.7 pF, +/-0.05 pF, 0603, ATC	1
C11	CAP, 20 pF, +/-5%, 0603, ATC	1
C15	CAP, 1.0 UF, 100V, 10%, X7R, 1210	1
C16	CAP, 33 UF, 20%, G CASE	1
J1, J2	CONN, SMA, PANEL MOUNT JACK, FLANGE, 4-HOLE, BLUNT POST	2
	PCB, RO4350, 0.020" THK	1
	BASEPLATE, CGH35015, 2.60 X 1.7	1
J3	HEADER RT>PLZ .1CEN LK 5POS	1
	2-56 SOC HD SCREW 1/4 SS	4
	#2 SPLIT LOCKWASHER SS	4
Q1	CGHV27030S, QFN	1

## **CGHV27030S-AMP3 Application Circuit**

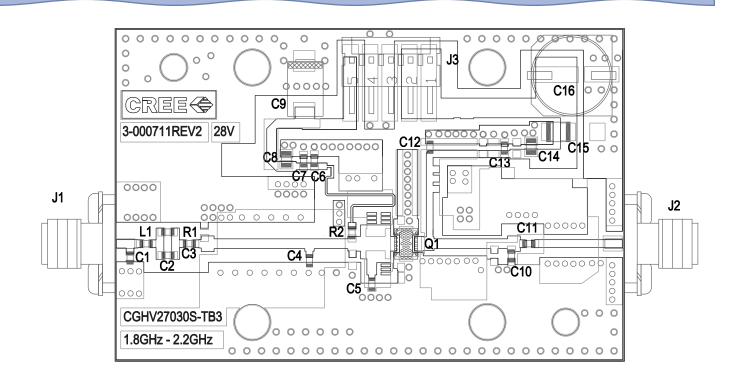




#### CGHV27030S-AMP3 Application Circuit Schematic, 28 V



### CGHV27030S-AMP3 Application Circuit Outline, 28 V

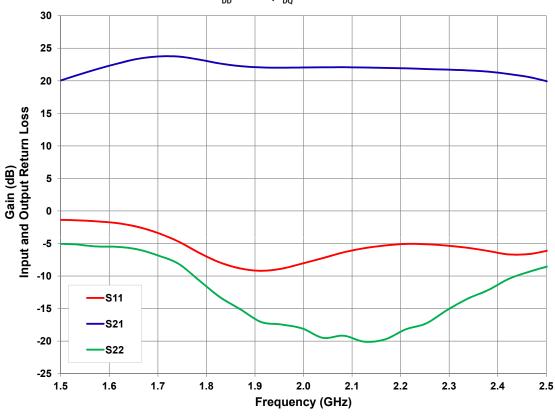




# Electrical Characteristics When Tested in CGHV27030S-AMP4, 50 V, 1.8 - 2.2 GHz

Parameter	1.8 GHz	2.0 GHz	2.2 GHz	Units
Small Signal Gain	22	22	21	dB
Adjacent Channel Power @ P <sub>OUT</sub> =5 W	-39	-38	-37	dBc
Drain Efficiency @ P <sub>out</sub> = 5 W	31	32	33	%
Input Return Loss	5	7	6	dB

Figure 10. - Small Signal Gain and Return Losses vs Frequency  $V_{\rm DD}$  = 50 V,  $I_{\rm DO}$  = 0.13 A



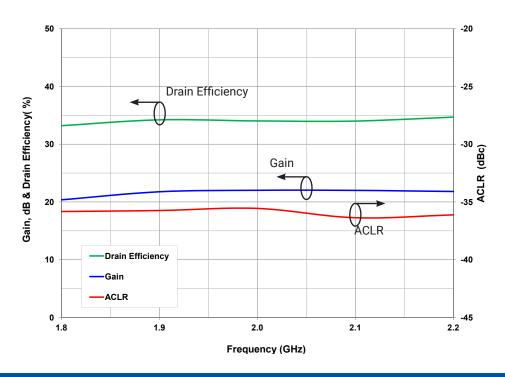




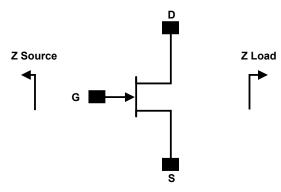
0 45 ACLR\_1p8 -5 40 -ACLR\_2p0 -10 ACLR\_2p2 -DE\_1p8 -15 DE\_2p0 ACLR (dBc) Drain Efficiency ( %) 25 -20 DE\_2p2 -25 20 -30 15 10 -35 -40 5 -45 0 20 22 24 26 30 32 34 36 38 Output Power (dBm)

Figure 11. - Typical Drain Efficiency and ACLR vs. Output Power  $V_{DD}$  = 50 V,  $I_{DQ}$  = 0.13 A, 1c WCDMA, PAR = 7.5 dB

Figure 12. - Typical Gain, Drain Efficiency and ACLR vs Frequency  $V_{\rm DD}$  = 50 V,  $I_{\rm DQ}$  = 0.13 A,  $P_{\rm AVE}$  = 5 W, 1c WCDMA, PAR = 7.5 dB







Frequency (MHz)	Z Source	Z Load
1800	5.0 - j3.3	20.0 + j18.6
2000	6.4 - j3.3	17.8 + j19.1
2200	4.0 - j2.7	16.2 + j20.8

Note<sup>1</sup>:  $V_{DD}$  = 50 V,  $I_{DQ}$  = 0.13 A in the DFN package. Note<sup>2</sup>: Impedances are extracted from the CGHV27030S-AMP4 application circuit and are not source and load pull data derived from the transistor

### CGHV27030S-AMP4 Bill of Materials

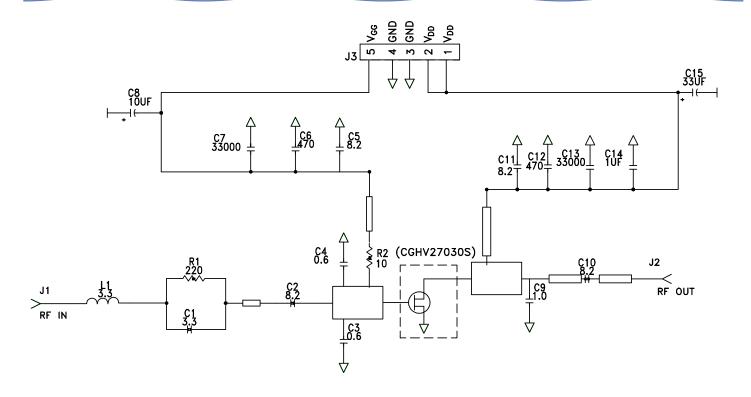
Designator	Description	Qty
R1	RES, 220, OHM, +/-1%, 1/16W, 0603	1
R2	RES, 10, OHM, +/-1%, 1/16W, 0603	1
L1	IND, 3.3 nH, +/-5%, 0603, JOHANSON	1
C1	CAP, 3.3 pF, +/-0.1 pF, 0603, ATC	1
C2, C5, C10, C11	CAP, 8.2 pF, +/-5%, 0603, ATC	1
C3, C4	CAP, 0.6 pF, +/-0.1 pF, 0603, ATC	2
C6, C12	CAP, 470 pF, 5%, 100V, 0603, X	2
C7, C13	CAP, 33000 pF, 0805, 100V. X7R	2
C8	CAP 10 UF 16 V TANTALUM	1
C9	CAP, 1.0 pF, +/-0.1 pF, 0603, ATC	1
C14	CAP, 1.0 UF, 100V, 10%, X7R, 1210	1
C15	CAP, 33 UF, 20%, G CASE	1
J1, J2	CONN, SMA, PANEL MOUNT JACK, FLANGE, 4-HOLE, BLUNT POST	2
PCB	PCB, RO4350, 0.020" THK	1
J3	HEADER RT>PLZ .1CEN LK 5POS	1
Q1	CGHV27030S, QFN	1

## **CGHV27030S-AMP4 Application Circuit**

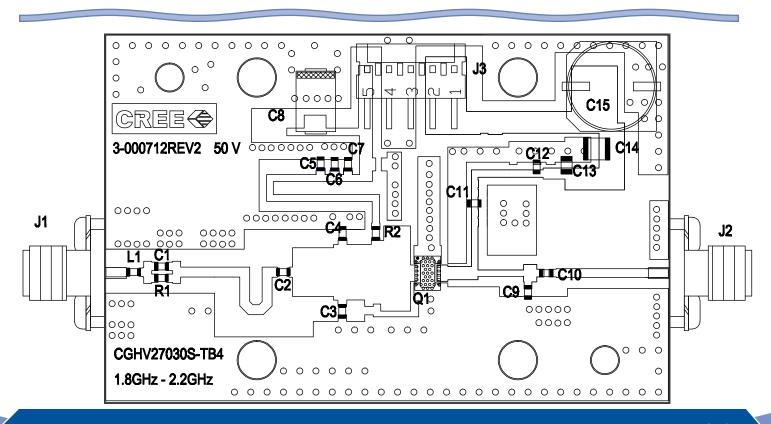




#### CGHV27030S-AMP4 Application Circuit Schematic, 50 V



### CGHV27030S-AMP4 Application Circuit Outline, 50 V

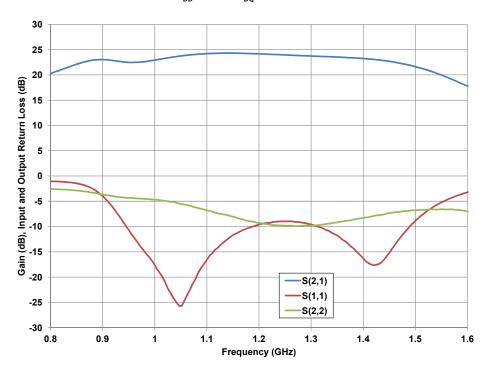




# Electrical Characteristics When Tested in CGHV27030S-AMP5, 50 V, 1.2 - 1.4 GHz

Parameter	1.2 GHz	1.3 GHz	1.4 GHz	Units
Output Power @ P <sub>IN</sub> = 27 dBm	35.5	33.5	32.5	W
Gain @ P <sub>IN</sub> = 27 dBm	18.5	18.25	18.1	dB
Drain Efficiency @ P <sub>IN</sub> = 27 dBm	71	67	65	%

Figure 13. - Small Signal Gain and Return Losses vs Frequency  $V_{_{\rm DD}}$  = 50 V,  $I_{_{\rm DQ}}$  = 0.125 A





### Typical Performance in Application Circuit CGHV27030S-AMP5

20

13

15

17

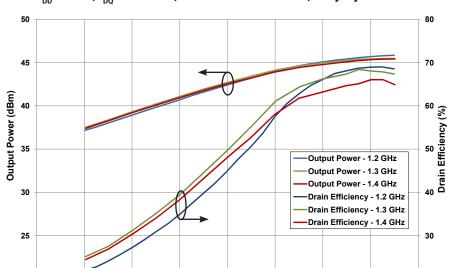


Figure 14. - Typical Output Power and Drain Efficiency Input Power  $V_{DD}$  = 50 V,  $I_{DQ}$  = 0.125 A, Pulse Width = 100 us, Duty Cycle = 10 %

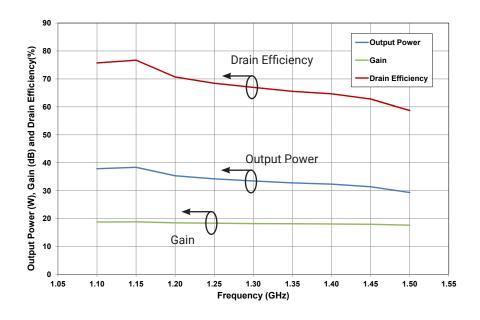
Figure 15. - Typical Output Power, Gain, and Drain Efficiency vs Frequency  $V_{DD}$  = 50 V,  $I_{DQ}$  = 0.125 A,  $P_{IN}$  = 27 dBm, Pulse Width = 100 us, Duty Cycle = 10 %

21

Input Power (dBm)

25

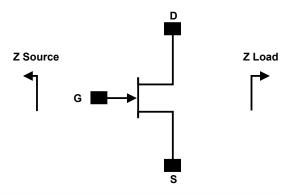
27



20

29





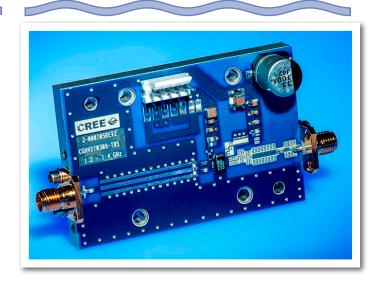
Frequency (MHz)	Z Source	Z Load
1200	8.6 + j5.4	25.4 + j29.2
1300	8.7 + j5.1	27.6 + j30.5
1400	7.4 + j5.2	30.1 + j31.8

Note¹:  $V_{DD}$  = 50 V,  $I_{DQ}$  = 0.125 A in the DFN package. Note²: Impedances are extracted from the CGHV27030S-AMP5 application circuit and are not source and load pull data derived from the transistor

### CGHV27030S-AMP5 Bill of Materials

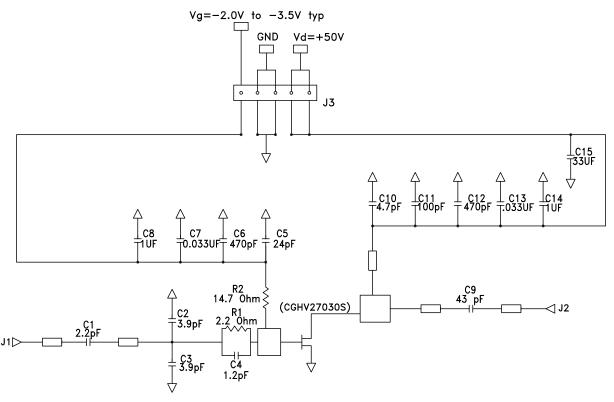
Designator	Description	Qty
R1	RES, 2.2, OHM, 1/10W 5% 0603 SMD	1
R2	RES, 1/16W, 0603, 1%, 14.7 OHMS	1
C1	CAP, 2.2 pF, +/-0.1 pF, 0603, ATC	1
C2, C3	CAP, 3.9 pF, +/-0.1 pF, 0603, ATC	2
C4	CAP, 1.2 pF, +/-0.1 pF, 0603, ATC	1
C5	CAP, 24 pF, +/-5%, 0603, ATC	1
C6, C12	CAP, 470 pF, 5%, 100V, 0603, X	2
C7, C13	CAP, 33000 pF, 0805, 100V, Z7R	2
C8, C14	CAP, 1.0 UF, 100V, 10%, X7R, 1210	2
C9	CAP, 43 pF, +/-5%, 0603, ATC	1
C10	CAP, 4.7 pF, +/-0.1 pF, 0603, ATC600S	1
C11	CAP, 100.0 pF, +/-5%, 0603, ATC	1
C15	CAP, 33 UF, 20%, G CASE	
J1, J2	CONN, SMA, PANEL MOUNT JACK, FLANGE, 4-HOLE, BLUNT POST	2
PCB	PCB, RO4350, L-BAND, 1.7" X 2.6"	1
J3	HEADER RT>PLZ .1CEN LK 5POS	1
Q1	CGHV27030S, QFN	1

## **CGHV27030S-AMP5 Application Circuit**

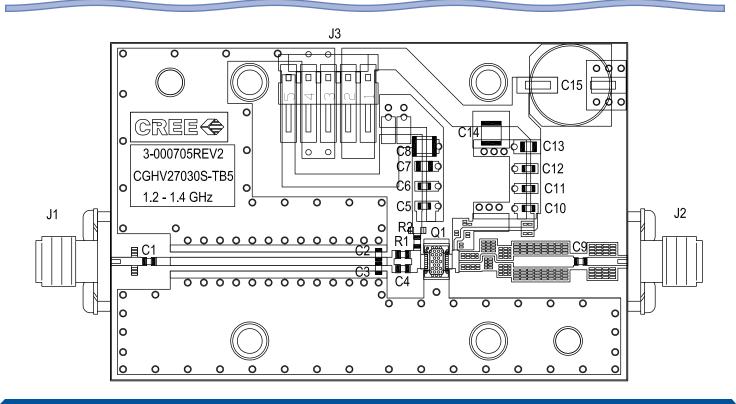




### CGHV27030S-AMP5 Application Circuit Schematic, 50 V



## CGHV27030S-AMP5 Application Circuit Outline, 50 V





## **CGHV27030S Power Dissipation De-rating Curve**

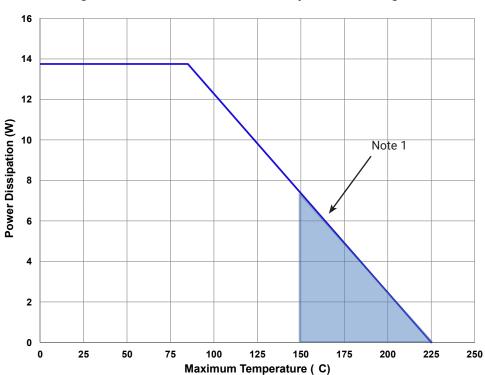


Figure 16. - CGHV27030S Power Dissipation De-Rating Curve

Note 1. Area exceeds Maximum Case Temperature (See Page 2).

## **Electrostatic Discharge (ESD) Classifications**

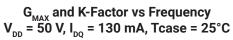
Parameter	Symbol	Class	Test Methodology
Human Body Model	НВМ	1A (> 250 V)	JEDEC JESD22 A114-D
Charge Device Model	CDM	2 (125 V to 250 V)	JEDEC JESD22 C101-C

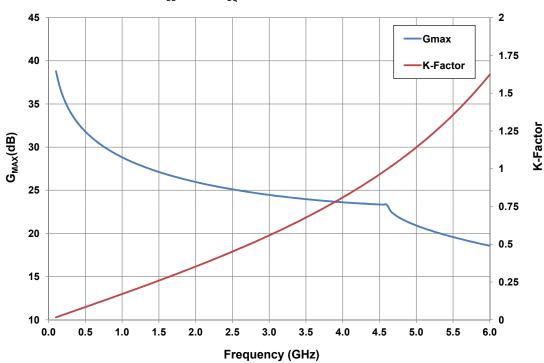
# Moisture Sensitivity Level (MSL) Classification

Parameter	Symbol	Level	Test Methodology
Moisture Sensitivity Level	MSL	3 (168 hours)	IPC/JEDEC J-STD-20



# **Typical Performance**

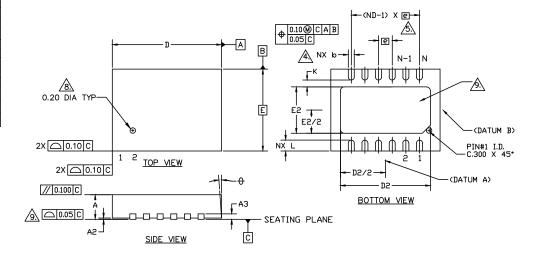






## Product Dimensions CGHV27030S (Package 3 x 4 DFN)

Α3	(	0.203 REF.			
Φ	0		12	2	
D		4.00 BSC			
Ε		3.00 BSC			
е		0.50 BSC			
N		12		3	
ND		6			
L	0.35	0.35 0.40 0.45			
Ь	0.17	0.17 0.22 0.27			
D2	3.20	3.20 3.30 3.40			
E2	1.60	1.60 1.7 1.80			
K	0.20				



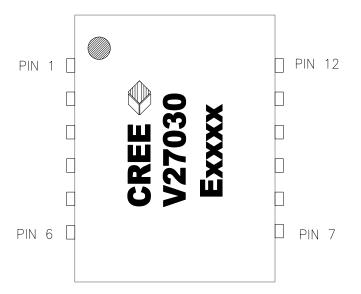
#### NOTES:

- 1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M 1994. 2. ALL DIMENSIONS ARE IN MILLIMETERS,  $\varTheta$  IS IN DEGREES.
- N IS THE TOTAL NUMBER OF TERMINALS.
- 3. N IS THE TOTAL NUMBER OF TERMINALS.

  DIMENSION 6 APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN .15 AND .30mm FROM TERMINAL TIP.

  S. ND REFERS TO THE NUMBER OF TERMINALS ON D SIDE
- 6. MAXIMUM PACKAGE WARPAGE IS .05 mm.
- MAXIMUM ALLOWABLE BURRS IS .076 mm IN ALL DIRECTIONS.
- PIN #1 ID ON TOP WILL BE LASER MARKED.
- MUNILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.
- 10. THIS DRAWING CONFORMS TO JEDEC REGISTERED OUTLINE MO-229.
- 11. ALL PLATED SURFACES ARE AU.

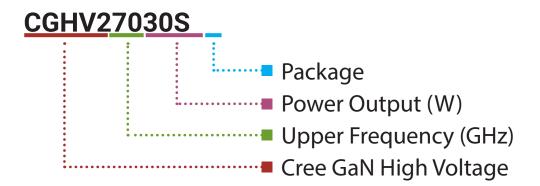
Pin	Input/Output
1	GND
2	NC
3	RF IN
4	RF IN
5	NC
6	GND
7	GND
8	NC
9	RF OUT
10	RF OUT
11	NC
12	GND



Note: Leadframe finish for 3x4 DFN package is Nickel/Palladium/Gold. Gold is the outer layer.



## **Part Number System**



Parameter	Value	Units
Upper Frequency <sup>1</sup>	2.7	GHz
Power Output	30	W
Package	Surface Mount	-

Table 1.

**Note**<sup>1</sup>: Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.

Character Code	Code Value
А	0
В	1
С	2
D	3
E	4
F	5
G	6
Н	7
J	8
K	9
Examples:	1A = 10.0 GHz 2H = 27.0 GHz

Table 2.



# **Product Ordering Information**

Order Number  CGHV27030S	Description  GaN HEMT	<b>Unit of Measure</b> Each	Image  V275505
CGHV27030S-AMP1	Test board without GaN HEMT, 50 V 2.5-2.7 GHz	Each	CRES CONTROL OF THE PROPERTY O
CGHV27030S-AMP2	Test board with GaN HEMT installed 28 V 2.5-2.7 GHz	Each	
CGHV27030S-AMP3	Test board with GaN HEMT installed 28 V 1.8-2.2 GHz	Each	CREECE SUPPLIES OF STREET
CGHV27030S-AMP4	Test board with GaN HEMT installed 50 V 1.8-2.2 GHz	Each	GRES AND
CGHV27030S-AMP5	Test board with GaN HEMT installed 50 V 1.2-1.4 GHz	Each	CREE CONTROL OF THE PARTY OF TH
CGHV27030S-TR	Delivered in Tape ard Reel	250 parts / reel	



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